# CM1240

# Dual-Voltage ESD Protection Array for USB Ports

#### **Product Description**

The CM1240 is a 4-channel ESD protection array. Three channels of the CM1240 are low voltage (LV) diodes, which have a capacitance of 7 pF enabling them to protect high speed I/O ports while providing robust ESD protection. The other channel of the CM1240 is a high voltage (HV) diode which has a capacitance of 25 pF enabling it to protect power supply inputs or OLED power rails, etc.

The parts integrate avalanche-type ESD diodes, which provide a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The ESD protection diodes are designed and characterized to safely dissipate ESD strikes of ±8 kV, the maximum requirement of the IEC61000-4-2 international standard. Using the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD, the pins are protected for contact discharges of greater than ±16 kV.

This device is particularly well suited for portable electronics (e.g. wireless handsets, PDAs, notebook computers) because of its small package format and easy-to-use pin assignments. In particular, the CM1240 is ideal for protecting USB or mini-USB ports operating at full speed (12 Mbps).

#### **Features**

- Four Channels of ESD Protection
- ±8 kV ESD Protection (IEC61000-4-2, Contact Discharge)
- ±16 kV ESD Protection (HBM)
- SOT-563 Space-saving Package
- 16 V Clamp on V<sub>CC</sub>
- These Devices are Pb-Free and are RoHS Compliant

#### **Applications**

- USB and Mini-USB Applications
- I/O Port Protection for Mobile Handsets
- Wireless Handsets



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#### **MARKING DIAGRAM**



L40 = Specific Device Code M = Month Code ■ = Pb-Free Package

#### ORDERING INFORMATION

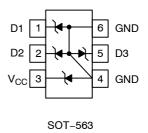
/ice	Package	Shipping <sup>†</sup>
-F4SE		5000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

**Table 1. PIN DESCRIPTIONS** 

	6-pin SOT-563 Package					
Pin	Name	Description				
1	D1	Cathode Connection for Low Voltage ESD Diode				
2	D2	Cathode Connection for Low Voltage ESD Diode				
5	D3	Cathode Connection for Low Voltage ESD Diode				
3	$V_{CC}$	Cathode Connection for High Voltage ESD Diode				
-	NC	No Connect				
-	NC	No Connect				
-	NC	No Connect				
-	NC	No Connect				
4	GND	Anode-side Connection for All ESD Diodes				
6	GND	Anode-side Connection for All ESD Diodes				

#### **PACKAGE / PINOUT DIAGRAMS**



#### **SPECIFICATIONS**

# **Table 2. ABSOLUTE MAXIMUM RATINGS**

Parameter	Rating	Units
ESD Protection (HBM)	16	kV
Pin Voltages V <sub>CC</sub> to GND All Other Pins to GND	[GND – 0.3] to +13 [GND – 0.3] to +5.5	٧
Storage Temperature Range	-65 to +150	°C
Lead Temperature (soldering, 10 sec)	300	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

### **Table 3. STANDARD OPERATING CONDITIONS**

Parameter	Rating	Units
Operating Temperature Range	-40 to +85	°C

## CM1240

Table 4. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
C <sub>LV</sub>	LV Diode Capacitance at 3 Vdc; 1 MHz, 30 mVac			6		pF
C <sub>HV</sub>	HV Diode Capacitance at 3 Vdc; 1 MHz, 30 mVac			25		pF
I <sub>LV</sub>	LV Diode Leakage at +3.3 V reverse bias voltage			0.01	0.4	μΑ
I <sub>HV</sub>	HV Diode Leakage at +11 V reverse bias voltage			0.01	0.4	μΑ
V <sub>CL(LV)</sub>	LV Diode Signal Clamp Voltage: Positive Clamp, 10 mA Negative Clamp, –10 mA		5.6 -1.5	6.8 -0.8	9 -0.4	V
V <sub>CL(HV)</sub>	HV Diode Signal Clamp Voltage: Positive Clamp, 10 mA Negative Clamp, –10 mA		13 -1.5	16 -0.8	19 -0.4	V
V <sub>ESD</sub>	In-system ESD withstand voltage: Human Body Model (MIL-STD-883, method 3015) IEC 61000-4-2, contact discharge method	(Note 2)	±25 ±12			kV
R <sub>DYN(LV)</sub>	LV Diode Dynamic Resistance: Positive Negative			2.8 1.2		Ω
R <sub>DYN(HV)</sub>	HV Diode Dynamic Resistance: Positive Negative			1.0 0.7		Ω

Guaranteed at 25°C only
 ESD applied to input/output pins with respect to GND, one at a time. These parameters are guaranteed by design.

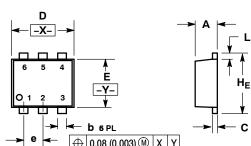
# **MECHANICAL CASE OUTLINE**





SOT-563, 6 LEAD CASE 463A ISSUE G

**DATE 23 SEP 2015** 



 $\oplus$ 0.08 (0.003) M X Y

STYLE 1: PIN 1. EMITTER 1 2. BASE 1 3. COLLECTOR 2

4. EMITTER 2 5 BASE 2 6. COLLECTOR 1

STYLE 4:

PIN 1. COLLECTOR COLLECTOR
 BASE

4. EMITTER 5. COLLECTOR 6. COLLECTOR

STYLE 7:

PIN 1. CATHODE 2. ANODE 3. CATHODE

 CATHODE
 ANODE 6. CATHODE

STYLE 10: PIN 1. CATHODE 1

2. N/C 3. CATHODE 2 4. ANODE 2

5 N/C 6. ANODE 1

STYLE 2: PIN 1. EMITTER 1 2. EMITTER2

3. BASE 2 4. COLLECTOR 2

5 BASE 1

6. COLLECTOR 1

STYLE 5: PIN 1. CATHODE CATHODE
 ANODE

4. ANODE 5. CATHODE 6. CATHODE

STYLE 8: PIN 1. DRAIN 2. DRAIN 3. GATE

4. SOURCE 5. DRAIN 6. DRAIN

STYLE 3: PIN 1. CATHODE 1 2. CATHODE 1 3. ANODE/ANODE 2

4. CATHODE 2 5. CATHODE 2

6. ANODE/ANODE 1

STYLE 6: PIN 1. CATHODE

2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE

6. CATHODE

STYLE 9: PIN 1. SOURCE 1 2. GATE 1

3. DRAIN 2

4. SOURCE 2 5. GATE 2 6. DRAIN 1

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS			MILLIMETERS INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.55	0.60	0.020	0.021	0.023
b	0.17	0.22	0.27	0.007	0.009	0.011
С	0.08	0.12	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.062	0.066
Е	1.10	1.20	1.30	0.043	0.047	0.051
е	0.5 BSC			(	0.02 BS0	
L	0.10	0.20	0.30	0.004	0.008	0.012
HF	1.50	1.60	1.70	0.059	0.062	0.066

#### **GENERIC** MARKING DIAGRAM\*



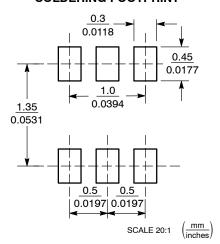
XX = Specific Device Code

= Month Code

= Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

## **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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